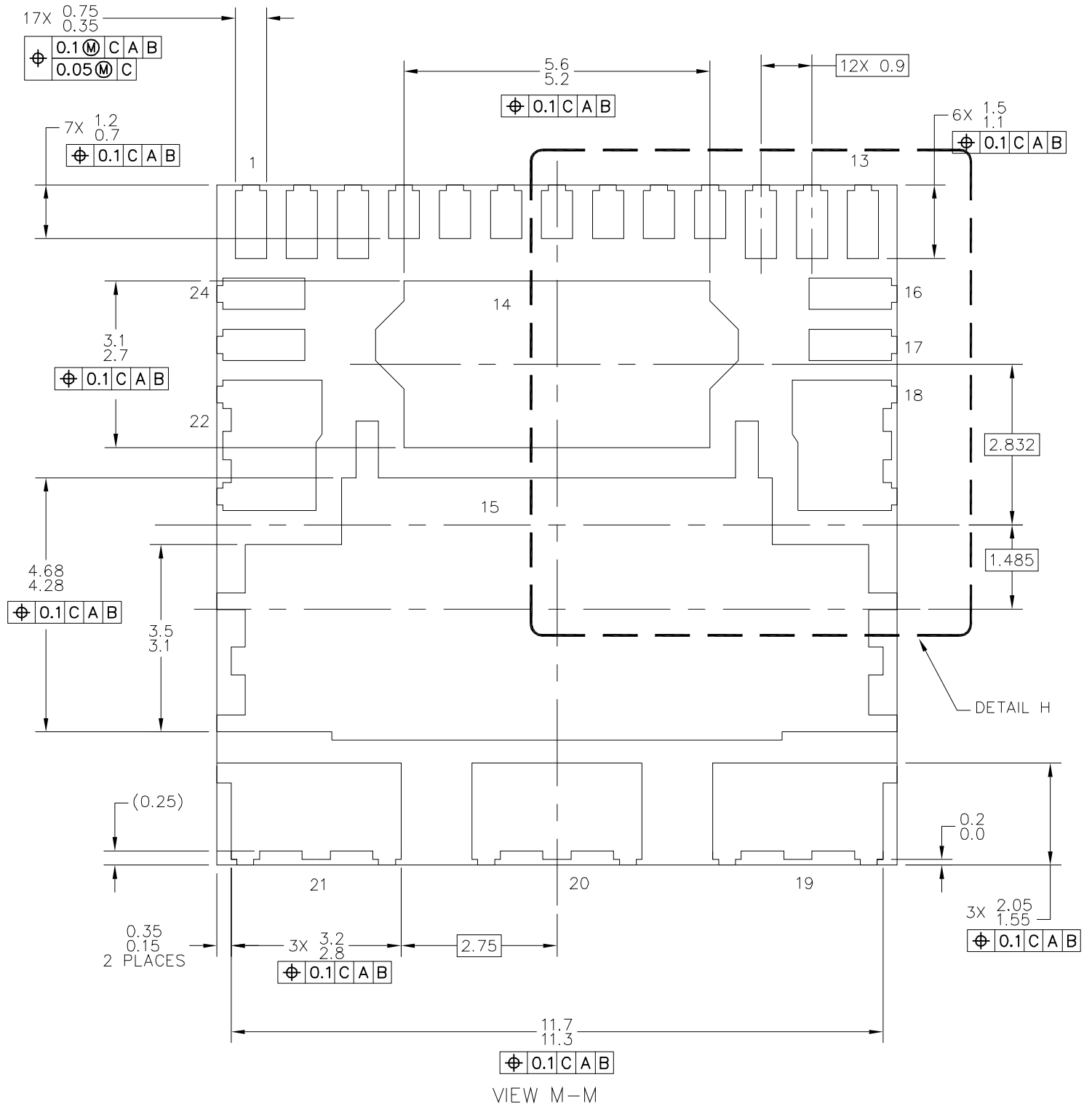
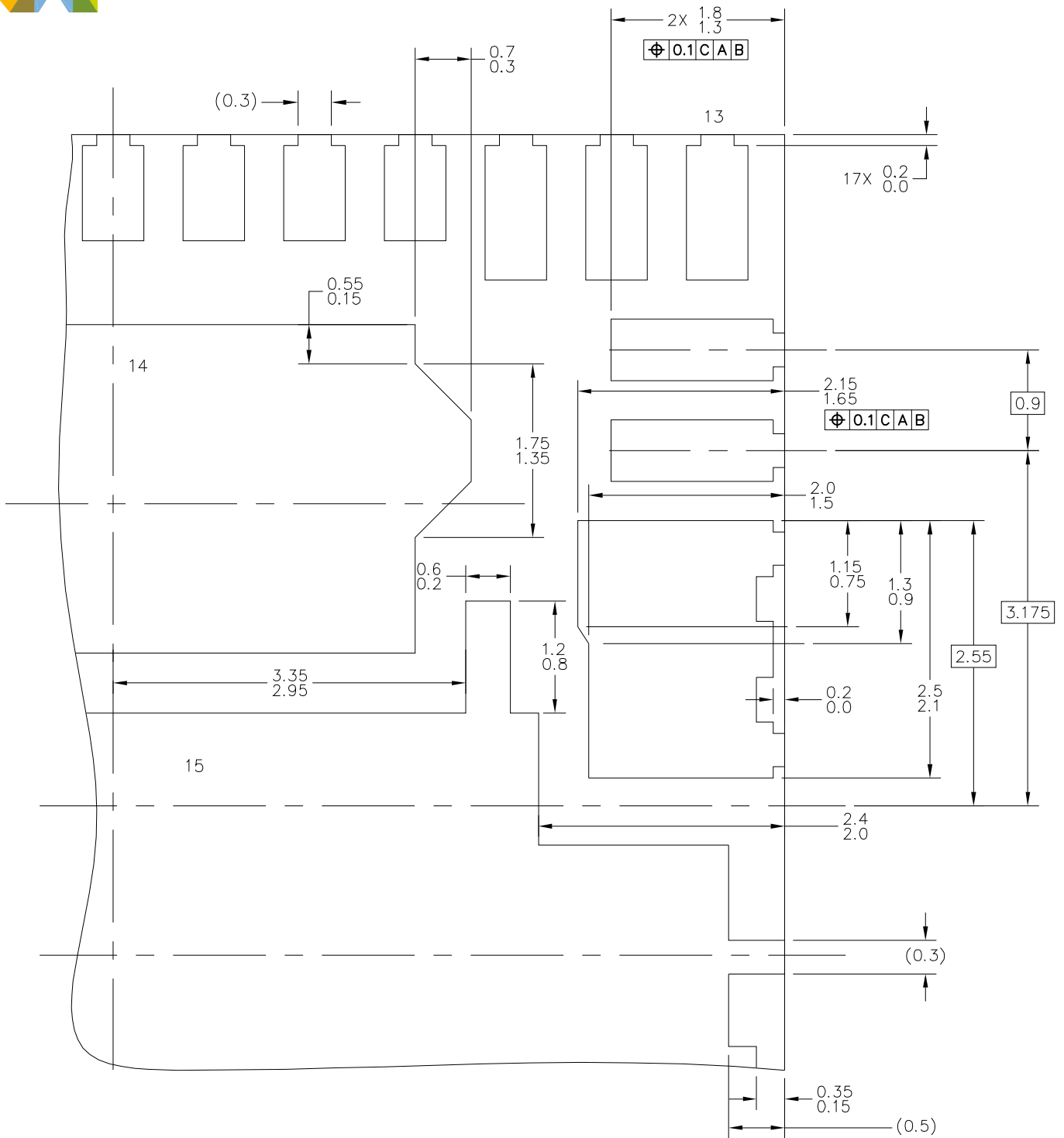


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TITLE: POWER QUAD FLAT NON-LEADED (PWR QFN) PACKAGE, 24 TERMINAL, 12X12X2.1, 0.9 PITCH	DOCUMENT NO: 98ARL10596D	REV: F
	STANDARD: NON-JEDEC	
	SOT1631-2	30 DEC 2015

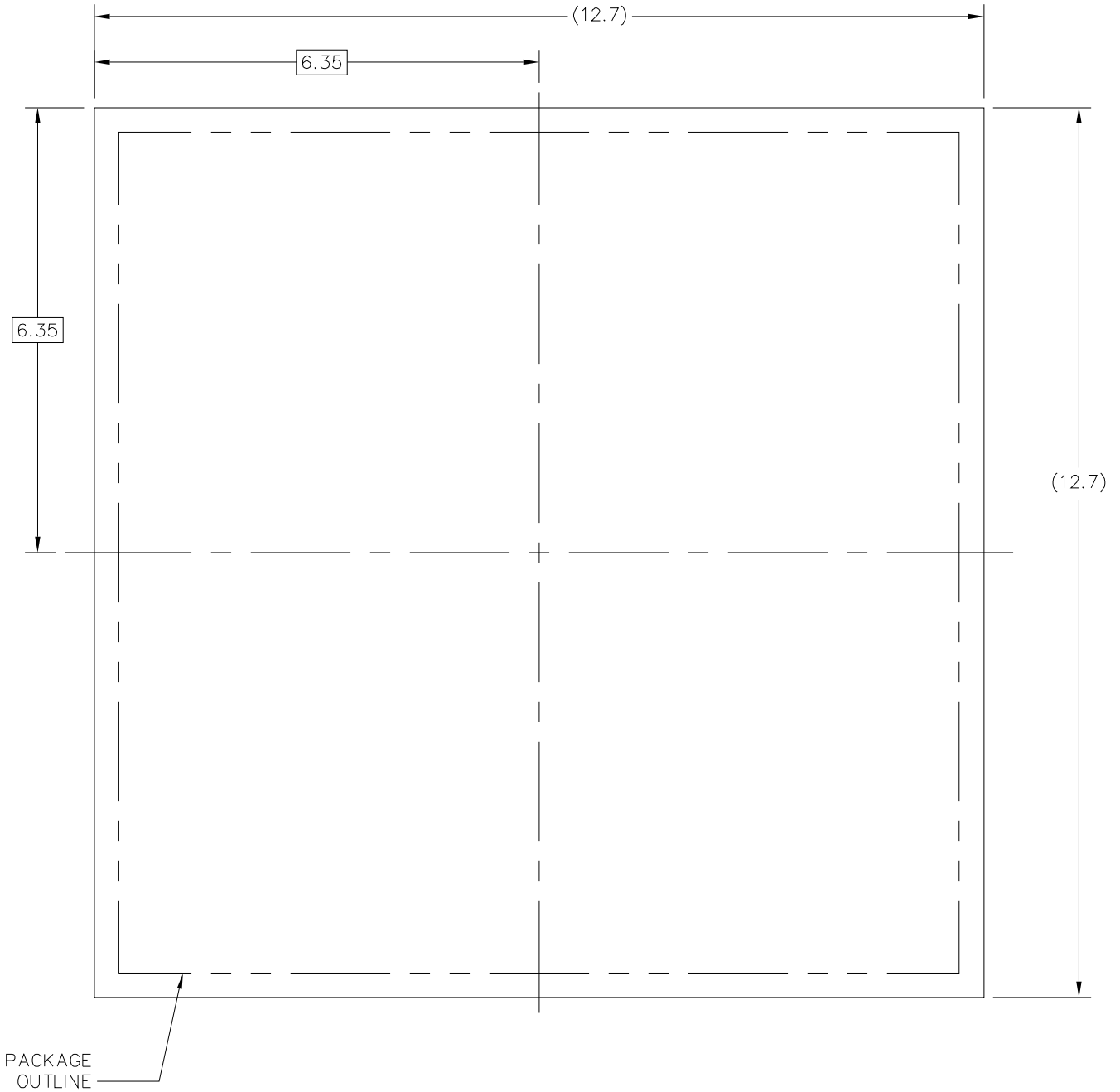


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TITLE: POWER QUAD FLAT NON-LEADED (PWR QFN) PACKAGE, 24 TERMINAL, 12X12X2.1, 0.9 PITCH	DOCUMENT NO: 98ARL10596D	REV: F
	STANDARD: NON-JEDEC	
	SOT1631-2	30 DEC 2015



DETAIL H

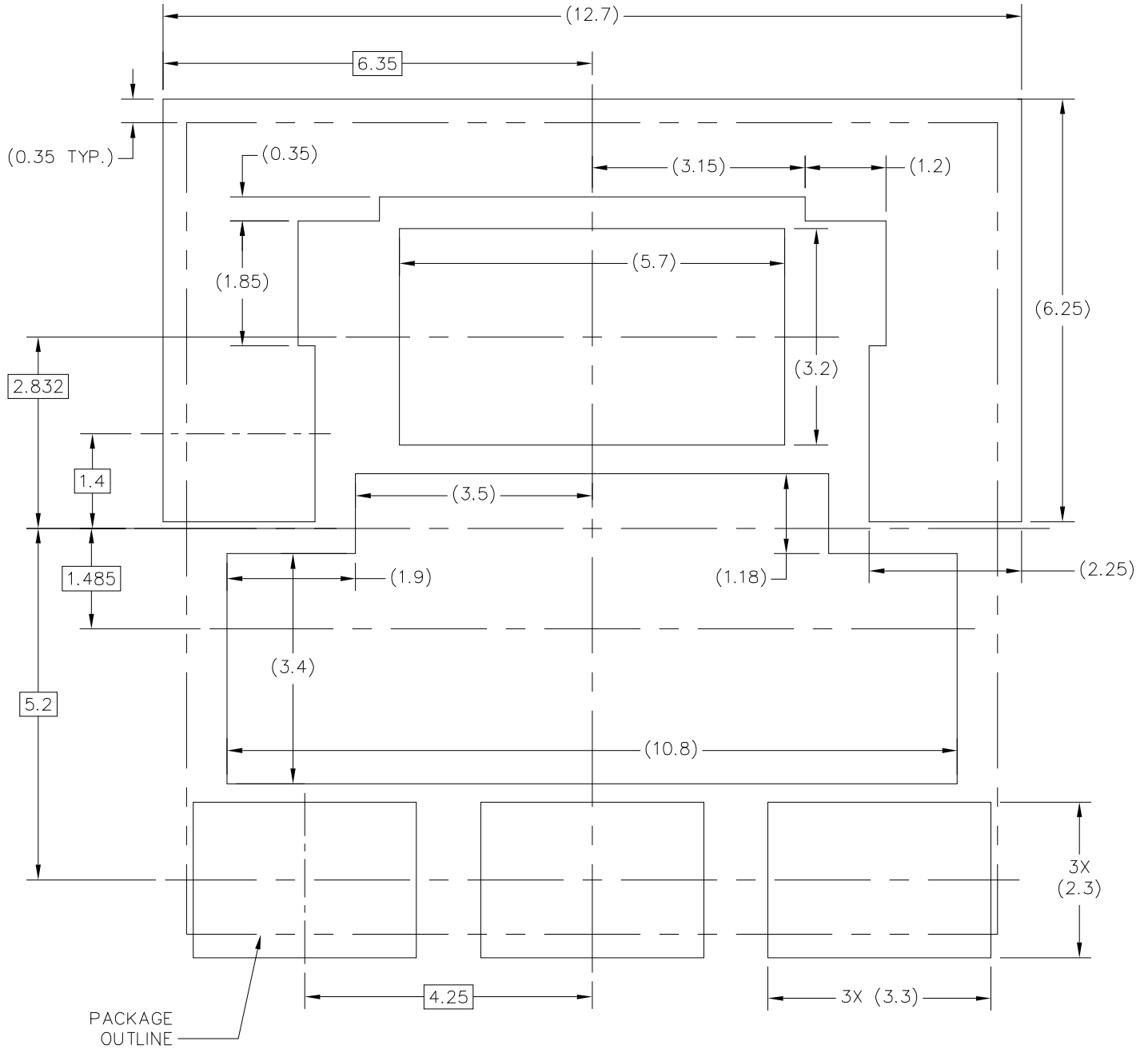
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	STANDARD: NON-JEDEC	
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PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN 1

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL / SPECIFIC REQUIREMENTS.

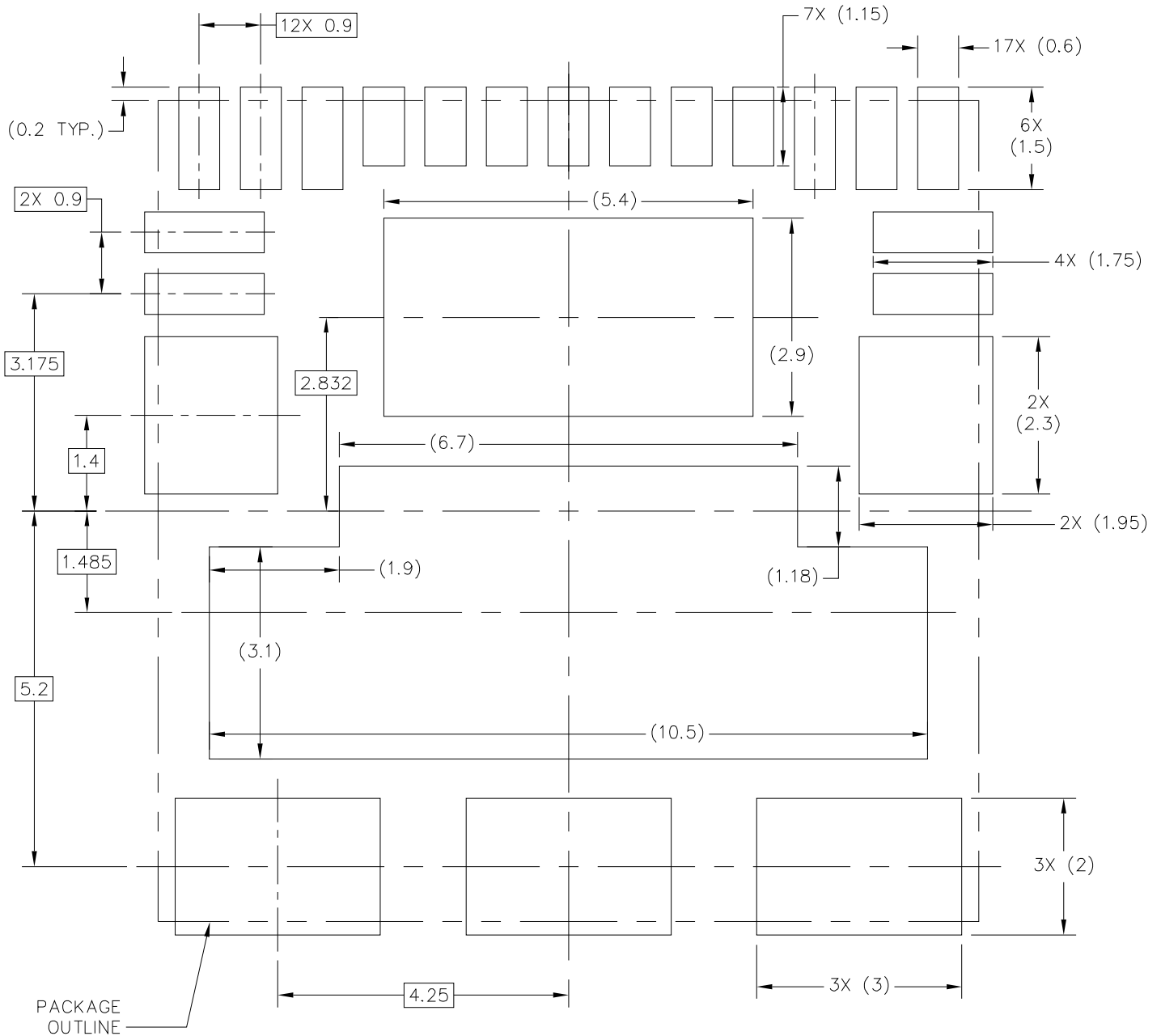
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TITLE: POWER QUAD FLAT NON-LEADED (PWR QFN) PACKAGE, 24 TERMINAL, 12X12X2.1, 0.9 PITCH		DOCUMENT NO: 98ARL10596D	REV: F
		STANDARD: NON-JEDEC	
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PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN 2

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL / SPECIFIC REQUIREMENTS.

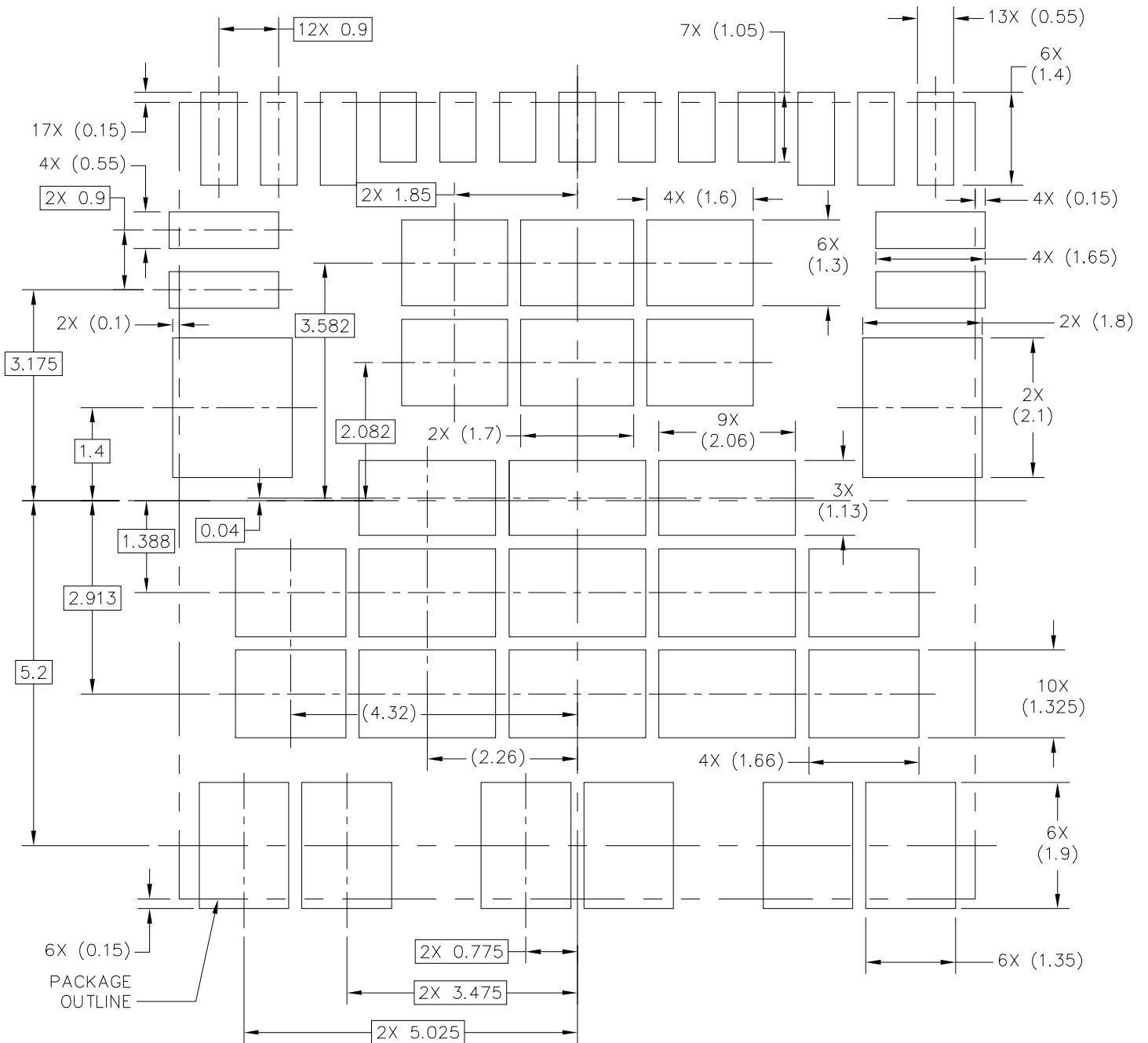
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TITLE: POWER QUAD FLAT NON-LEADED (PWR QFN) PACKAGE, 24 TERMINAL, 12X12X2.1, 0.9 PITCH		DOCUMENT NO: 98ARL10596D	REV: F
		STANDARD: NON-JEDEC	
		SOT1631-2	30 DEC 2015



PCB CU GUIDELINES – I/O PADS & SOLDERABLE AREAS

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		SOT1631-2	30 DEC 2015




### SOLDER PASTE STENCIL GUIDELINES

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL / SPECIFIC REQUIREMENTS.

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		STANDARD: NON-JEDEC	
		SOT1631-2	30 DEC 2015



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFP-N.
4.  COPLANARITY APPLIES TO LEADS AND CORNER LEADS.
5. MINIMUM METAL GAP IS GUARANTEED TO BE 0.25MM.

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		STANDARD: NON-JEDEC	
		SOT1631-2	30 DEC 2015